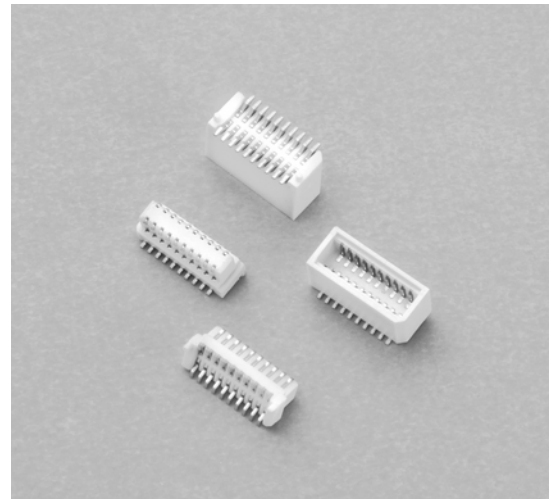


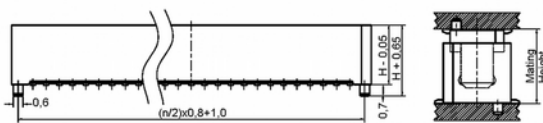
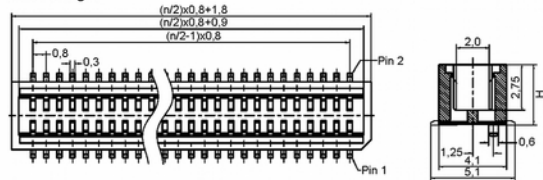
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplastischer Kunststoff, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Farbe <i>Colour</i>	Weiss <i>White</i>
Kontaktmaterial <i>Contact Material</i>	Phosphorbronze <i>Phosphor bronze</i>
Kontaktoberfläche <i>Contact Surface</i>	Gold über Nickel <i>Gold over nickel</i>
Lötbarkeit <i>Solderability</i>	IEC 60512-12A <i>IEC 60512-12A</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 40mΩ <i>< 40mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 100MΩ <i>> 100MΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	500V _{AC} <i>500V_{AC}</i>
Nennstrom <i>Current Rating</i>	0,5A <i>0.5A</i>
Temperaturbereich <i>Temperature Range</i>	-40°C ... +105°C <i>-40°C ... +105°C</i>
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>

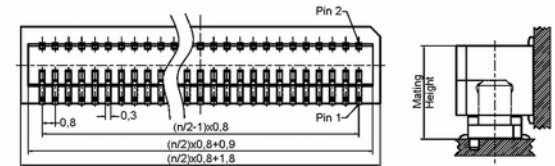
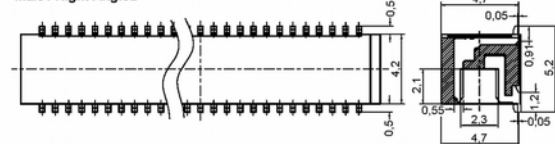


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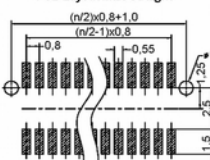
Male / Straight



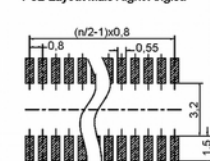
Male / Right Angled



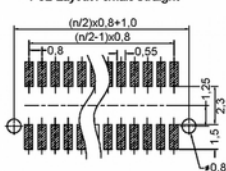
PCB Layout Male Straight



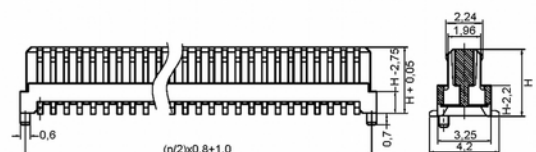
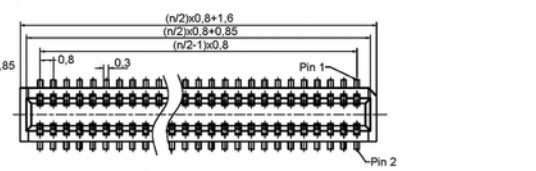
PCB Layout Male Right-Angled



PCB Layout Female Straight



Female



Mating Height		
	Female	
Male	Type 6 (H=3,55)	Type 7 (H=4,05)
Type 1 (H=3,65)	4,5	5,0
Type 2 (H=4,15)	5,0	5,5
Type 3 (H=5,15)	6,0	6,5
Type 4 (H=5,65)	6,5	7,0
Type 5 (H=4,70)	5,65	6,15

Series

5080

Type*

1

Contacts*

040

Plating

00

Package

TR

- 1 Stift gerade / Male straight H=3.65
- 2 Stift gerade / Male straight H=4.15
- 3 Stift gerade / Male straight H=5.15
- 4 Stift gerade / Male straight H=5.65
- 5 Stift gewinkelt / Male right angled H=4.70
- 6 Buchse gerade / Female straight H=3.55
- 7 Buchse gerade / Female straight H=4.05

**020/030/040/050/060/
060/070/080/090/100**
Andere Polzahlen auf Anfrage.
More contact options on request.

00 Au

TR Tape & Reel

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
* **This is an order example** - please replace by your specifications.

Informationen zum Reflow-Lötverfahren

Reflow Soldering Information

Reflow-Lötempfehlung

Reflow Soldering Recommendation

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150°C
Temperatur Maximum T_{Smax}	200°C
Dauer $T_{Smin} - T_{Smax}$	60-180s
Temperatur Lötbereich T_L	217°C
Verweildauer oberhalb T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Höchsttemperatur T_P	260°C ±5
Dauer Höchsttemperatur	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 8 min

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150°C
Maximum Temperatur T_{Smax}	200°C
Duration $T_{Smin} - T_{Smax}$	60-180s
Soldering Range Temperature T_L	217°C
Duration above T_L	60-180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3°C / s
Peak Temperature T_P	260°C ±5
Duration Peak Temperature	20-40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6°C / s
Duration 25°C - Peak Temp. T_P	Max. 8min

